Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	semiconductor adj substrate and organic adj substrate and pad and solder and ("coefficent of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:08
S2	6	("5471090" | "6005292" | "6046910" | "6118181" | "6232668" | "6271597").PN.	USPAT	OR	ON	2002/11/05 12:59
S3	0	"6310403".URPN.	USPAT	OR	ON	2002/11/05 13:02
S4	6	("5471090" | "6005292" | "6046910" | "6118181" | "6232668" | "6271597").PN.	USPAT	OR	ON	2002/11/05 13:02
S5	9	("3842189" | "4056681" | "4647959" | "4949148" | "5214308" | "5302854" | "5331513" | "5528461" | "5657207").PN.	USPAT	OR	ON	2002/11/05 13:02
S6	5	"6046910".URPN.	USPAT	OR	ON	2002/11/05 13:03
S7	4345	"coefficent of thermal expansion" or cte	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:16
S8	31	((257/786).CCLS.) and ("coefficent of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:06
S9	1299	c4 same solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:07
S10	169	("coefficent of thermal expansion" or cte) and (c4 same solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:55
S11	327	gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:16
S12	19	("coefficent of thermal expansion" or cte) and gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:18

S13	0	underfill adj material same gigapascal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S14	775	underfill adj material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S15	188	("coefficent of thermal expansion" or cte) and (underfill adj material)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:19
S16	143	conductive adj pad and solder and bump and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/05 13:41
S17	1235	(257/786).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/06 09:10
S18	195	c4 and solder and ("coefficent of thermal expansion" or cte)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:51
S19	7841	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:46
S20	20	("coefficent of thermal expansion" or cte) and (c4 same solder) and ((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 13:56
S21	2570	(lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 15:00
S22	14566	flip adj chip or flipchip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:47

S23	386	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4) and (flip adj chip or flipchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 14:47
S24	245	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2002/11/06 15:01
S25	69	larger near pad and smaller near pad and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/11 10:14
S26	6	("4673772" | "5616520" | "5761048" | "5859407" | "5907187" | "6093964").PN.	USPAT	OR	ON	2003/11/11 10:23
S27	1	"6285083".URPN.	USPAT	OR	ON	2003/11/11 10:25
S28	2	"6274474".URPN.	USPAT	OR	ON	2003/11/11 10:32
S29	0	beriner.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:41
S30	670	bernier.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:41
S31	7	solder adj ball and bernier.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:43
S32	6925	carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or "white.in"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:44
S33	20	solder adj ball and (carey.in. or gramatzki.in. or homa.in. or langevin.in. or tran.in. or "white.in")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2003/11/18 13:45
S34	57	"5075965".URPN.	USPAT	OR	ON	2003/11/18 13:50
S35	0	"6330967".URPN.	USPAT	OR	ON	2003/11/18 13:54

S36	25	("4545610" | "5060844" | "5075965" | "5161729" | "5221038" | "5234152" | "5372298" | "5429292" | "5470787" | "5473814" | "5580668" | "5591941" | "5634268" | "5639696" | "5675889" | "5729896" | "5796591" | "5808853" | "5825629" | "5912505" | "5953623" | "5965945" | "6121069" | "6130476" | "6162660").PN.	USPAT	OR	ON	2003/11/18 13:54
S37	27	organic adj substrate and (bump or electrode or pad) and solder adj ball and semiconductor adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/03 14:30
S38	2	("5889326").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:16
S39	9	("4724472" | "4970570" | "5028987" | "5422516" | "5508561" | "5611481" | "5640051" | "5640052" | "5641113").PN.	USPAT	OR	ON	2004/09/10 09:11
S40	27	"5889326".URPN.	USPAT	OR	ON	2004/09/10 09:12
S41	3540	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:17
S42	5624	organic adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:17
S43	60	(((257/747) or (257/759) or (257/773) or (257/779)).CCLS.) and (organic adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/10 09:28
S44	113	(257/474).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:29

S45	256	(257/747).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/10 09:29
S46	143	pad adj size and semiconductor adj die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:32
S47	2	organic adj substrate and S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 09:32
S48	10	("6166556").URPN.	USPAT	OR	ON	2004/12/10 09:41